

**Supplementary Information for:**

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*Plasmonic IQ Modulators with Attojoule per Bit*

*Electrical Energy Consumption*

**Supplementary Table 1: State-of-the-art IQ modulators**

Technology	Fiber-to-fiber loss [dB]	Device loss [dB]	$U_{\pi}L$ [Vmm]	Active Length [mm]	Line rate [Gbit/s]	EO Bandwidth	Reference
LiNbO <sub>3</sub>	~10	-	10-100	10-100	600	~40 GHz	<sup>1,2</sup>
GaAs	18	< 8 dB	90	30	150	~30 GHz	<sup>3</sup>
Si	~15	6.8 dB	30	4.5	350	~30 GHz	<sup>4</sup>
InP	9	~2 dB	~5	~3.6	448	~70 GHz	<sup>5,6</sup>
SOH	17.5*	8.5 dB	1	0.6	400	~40 GHz	<sup>7</sup>
Plasmonic-Organic Hybrid	19.2*	11.2	0.13	0.015	400	>500 GHz <sup>8</sup>	This work

\* fiber-to-fiber losses can be reduced to <10 dB when relying on a dedicated fabrication process

**Supplementary Table 2** Summary of investigated devices including fiber-to-fiber and on-chip losses.

<b>Device</b>	$L_{\text{active}}$ [ $\mu\text{m}$ ]	$w_{\text{slot}}$ [nm]	<b>On-chip loss</b> [dB]	<b>Photonic-plasmonic converter loss</b> [dB]	<b>Loss plasmonic section</b> [dB]	<b>Fiber-to-chip coupling loss</b> [dB per coupler]	<b>Fiber-to-fiber loss</b> [dB]
<b>IQ1 621</b>	15	130	~11.2	~1.7	~7.8	~4	19.2
<b>IQ2 622</b>	20	130	~14.5	~1.7	~11.1	~4	22.5
<b>IQ3 626</b>	20	130	~13.7	~1.7	~10.3	~4	21.7

**Supplementary Table 3** Measurements of Figure 2

Modulation	Device	$U_{\text{meas}50\Omega, \text{pp}}$	$E_{\text{bit}} \dagger$	BER	BER without el. equalizer	$P_{\text{opt}}$	$U_{\text{IQ, pk}}$
		[V]	[fJ bit <sup>-1</sup> ]			[dBm]	[V]
<b>50 GBd QPSK</b> (100 Gbit s <sup>-1</sup> )	IQ1	~2.0	10.2	6.86×10 <sup>-8*</sup>	3.3×10 <sup>-4</sup>	20	~2.0
	IQ2	1.92	12.4	4.96×10 <sup>-6†</sup>	5.9×10 <sup>-4†</sup>	15	1.92
	IQ3	1.92	12.4	8.25×10 <sup>-23*</sup>	1.9×10 <sup>-9*</sup>	18	1.92
<b>50 GBd 16QAM</b> (200 Gbit s <sup>-1</sup> )	IQ1	2.95	6.2	1.9×10 <sup>-4†</sup>	6.6×10 <sup>-3†</sup>	20	2.95
	IQ3	1.99	3.7	3.1×10 <sup>-4</sup>	6.8×10 <sup>-3</sup>	18	1.99
<b>100 GBd QPSK</b> (200 Gbit s <sup>-1</sup> )	IQ1	2.23	12.7	6.63×10 <sup>-9*</sup>	1.6×10 <sup>-6</sup>	18	2.23
	IQ2	3.45	40.0	1.26×10 <sup>-6*</sup>	5.2×10 <sup>-5</sup>	19	3.45
	IQ3	1.77	10.5	2.97×10 <sup>-7*</sup>	6.5×10 <sup>-5</sup>	18	1.77
<b>100 GBd 16QAM</b> (400 Gbit s <sup>-1</sup> )	IQ1	2.75	5.36	1.37×10 <sup>-2</sup>	6.3×10 <sup>-2</sup>	20	2.75
	IQ2	2.67	6.64	1.48×10 <sup>-2</sup>	6.4×10 <sup>-2</sup>	15	2.67
	IQ3	1.48	2.04	2.36×10 <sup>-2</sup>	4.5×10 <sup>-2</sup>	20	1.48

†Device capacitance of IQ1: 2.55 fF, for IQ2 and IQ3: 3.36 fF \*BER estimated from SNR, no/not enough errors counted for statistical relevant measured BER.<sup>9</sup> †Measurement performed with uncalibrated transmitter, BER estimated from SNR.

**Supplementary Table 4** Electrical energy consumption per bit at different symbol rates / modulation formats. All measurements performed with IQ3.

<b>Modulation</b>	$U_{\text{meas}50\Omega, \text{pp}}$	$\bar{E}_{\text{bit}}$	<b>BER</b>	$U_{\text{DAC, pp}}$	$U_{\text{IQ, pk}}$	<b>Attenuator</b>
<b>25 GBd QPSK</b> (50 Gbit s <sup>-1</sup> )	145 mV	0.07 fJ bit <sup>-1</sup>	$2.0 \times 10^{-3}$	350 mV	145 mV	6 dB
	187 mV	0.12 fJ bit <sup>-1</sup>	$1.66 \times 10^{-5*}$	450 mV	187 mV	6 dB
<b>50 GBd QPSK</b> (100 Gbit s <sup>-1</sup> )	326 mV	0.36 fJ bit <sup>-1</sup>	$2.0 \times 10^{-4}$	350 mV	326 mV	0 dB
<b>50 GBd 16 QAM</b> (200 Gbit s <sup>-1</sup> )	567 mV	0.30 fJ bit <sup>-1</sup>	$2.0 \times 10^{-2}$	650 mV	567 mV	0 dB
<b>100 GBd QPSK</b> (200 Gbit s <sup>-1</sup> )	426 mV	0.61 fJ bit <sup>-1</sup>	$1.4 \times 10^{-3}$	650 mV	426 mV	0 dB
<b>100 GBd 16QAM</b> (400 Gbit s <sup>-1</sup> )	1.48 V	2.04 fJ bit <sup>-1</sup>	$2.36 \times 10^{-2}$	650 mV	1.48 V	RF Amplifier

\* BER estimated from SNR, no/not enough errors counted for statistical relevant measured

BER.<sup>9</sup>

**Supplementary Table 5:** Operation at elevated temperatures. Measurement parameters of measurements M1-M5 shown in Figure 3. All measurements at 100 Gbit s<sup>-1</sup> (50GBd QPSK).

	Temp	Time at temp	Operating time	BER	EVM
	~22.5	>8h	7h	$8.4 \times 10^{-06*†}$	22.5 % <sup>†</sup>
<b>M1</b>	42 °C	20 min	7.8 h	$3.9 \times 10^{-8*}$	18.4 %
<b>M2</b>	65 °C	25 min	8.7 h	$6.38 \times 10^{-7*}$	20.1 %
<b>M3</b>	65 °C	70 min	9.4 h	$9.24 \times 10^{-6*}$	22.6 %
<b>M4</b>	75 °C	20 min	10 h	$7.08 \times 10^{-7*}$	20.4 %
<b>M5</b>	75 °C	80 min	11 h	$2.31 \times 10^{-6*}$	21.2 %

\* BER estimated from SNR, no/not enough errors counted for statistical relevant measured BER.<sup>9</sup> †Measurement performed with uncalibrated transmitter.

## Supplementary References

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